

FOR: BE SEMICONDUCTOR INDUSTRIES N.V.
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PRESS RELEASE

BE Semiconductor Industries Reports Provisional Accounting for Esec Acquisition

Duiven, the Netherlands, July 6, 2009. BE Semiconductor Industries N.V. ("the Company" or "Besi") (Euronext: BESI), a leading manufacturer of assembly equipment for the semiconductor industry, today announced that it completed the provisional accounting for the consolidated acquisition balance sheet of its Esec business unit as of April 1, 2009 per IFRS requirements. The valuation resulted in a one-time negative goodwill gain of approximately € 41 million. A summary of the purchase price accounting for the Esec transaction is approximately as follows (€ millions):

Fair value of net assets acquired	€ 46
Purchase price consideration	(5)
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Excess fair value of net assets acquired ("negative goodwill")	<u>€ 41</u>

As per IFRS, negative goodwill resulting from the transaction will be reported as a gain in Besi's operating results for the second quarter ending June 30, 2009.

Based in Cham, Switzerland, Esec is a leading global manufacturer of die bonding and wire bonding equipment with sales of approximately € 80 million in 2008 and an estimated installed base in excess of 9,000 systems worldwide.

Comment

Richard W. Blickman, Chief Executive Officer of Besi commented: "The acquisition of Esec is an important milestone in the development of our company. The funds received in the acquisition represent a financial cushion for operational losses, supplier obligations and incoming restructuring costs resulting from the transaction. In addition, our balance sheet position has strengthened as stockholders' equity increased significantly due to the negative goodwill gain and additional paid in capital from the transfer of shares in the acquisition. Furthermore, the transaction has significantly increased the breadth and scope of our product portfolio and our penetration of important global customer accounts. We are also pleased with the progress of the Esec business as measured by recent order activity for both die bonders and wire bonders affirming the market acceptance of its leading edge products and technology."

About BE Semiconductor Industries N.V.

BE Semiconductor Industries N.V. designs, develops, manufactures, markets and services die sorting, flip chip and multi-chip die bonding, wire bonding, packaging and plating equipment for the semiconductor industry's assembly operations. Its customers consist primarily of leading U.S., European and Asian semiconductor manufacturers, assembly subcontractors and industrial companies which utilize its products for both array connect and conventional leadframe manufacturing processes. For more information about Besi, please visit our website at www.besi.com.

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(table to follow)

Consolidated Esec Acquisition Balance Sheet

<i>(euro in thousands)</i>	April 1, 2009
ASSETS	
Cash and cash equivalents	19,462
Accounts receivable	5,362
Inventories	24,984
Receivable OC Oerlikon	8,196
Other current assets	4,102
Total current assets	62,106
Property, plant and equipment	2,007
In Process Research & Development	2,891
Deferred tax assets	1,053
Total non-current assets	5,951
Total assets	68,057
Liabilities	
Accounts payable	2,993
Provisions	11,765
Accrued liabilities	7,278
Total liabilities	22,036
Net Assets Acquired	46,021

The acquisition balance has been prepared in accordance with the measurement and recognition principles of IFRS 3 Business Combinations (2004).